

Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

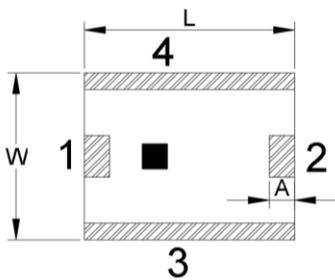
Specifications

NO.	Parameter	SPC
1	Frequency (MHz)	9400~9800
2	Insertion Loss (dB)@9600MHz 25°C	≤2.5
3	1dB Bandwidth (MHz)	≤700
4	3dB Bandwidth (MHz)	≤1000
5	VSWR(In BW)	≤2.0
6	Attenuation(dB)	≥50@7800MHz
7	In/Output Impedance (Ω)	50
8	Power(W)	1

Operating & Storage Condition (Component)
 Operation Temperature Range: -40°C ~ +85°C
 Storage Temperature Range: -40°C ~ +85°C

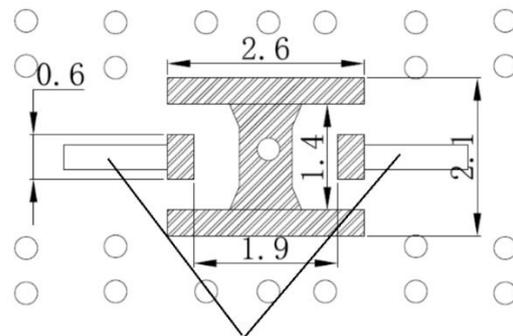
Storage Condition before Soldering (Included packaging material)
 Storage Temperature Range: +5 ~ +40 °C
 Humidity: 30 to 70% relative humidity

Construction



PIN	Connection	PIN	Connection
1	Input port	3	GND
2	Output port	4	GND

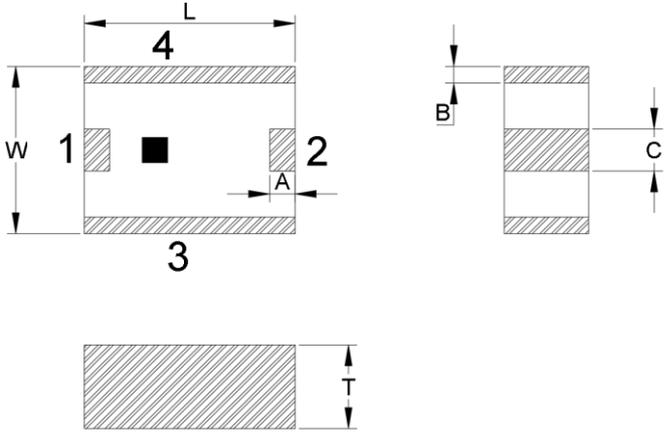
Mounting Considerations



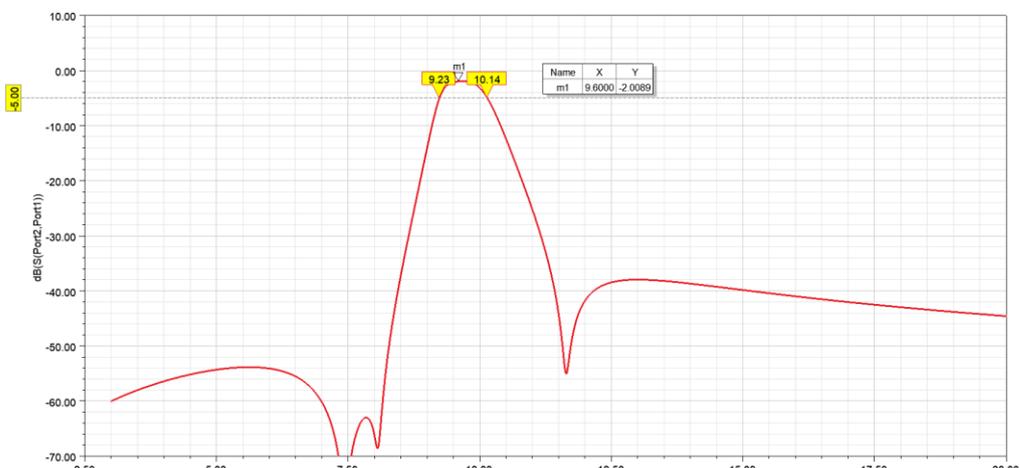
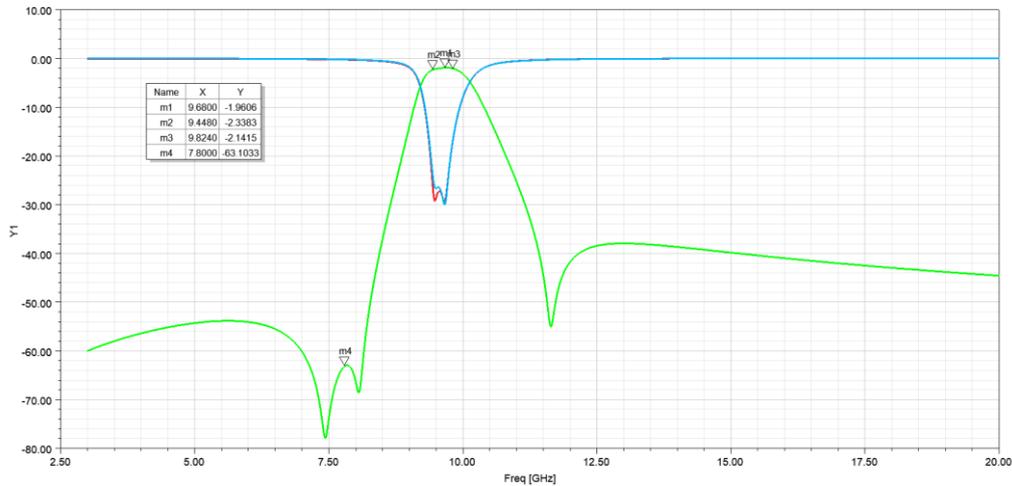
Line 50 Ω

Unit: mm

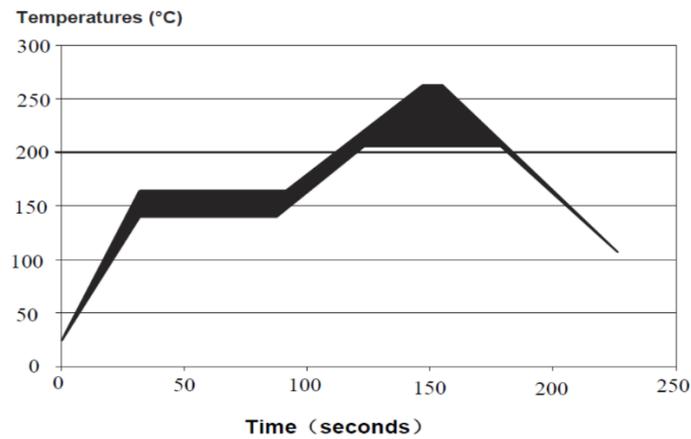
Dimensions

Figure	Symbol	Dimension (mm)
	L	2.50±0.20
	W	2.0±0.20
	T	1.0±0.20
	A	0.30±0.10
	B	0.20±0.10
	C	0.50±0.20

Typical Electrical Characteristics (T=25° C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.